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**Komatsu et al.**(10) **Pub. No.: US 2010/0154883 A1**(43) **Pub. Date: Jun. 24, 2010**(54) **METHOD OF MANUFACTURING  
CRYSTALLINE SILICON SOLAR CELLS  
WITH IMPROVED SURFACE PASSIVATION**(30) **Foreign Application Priority Data**

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**SAN FRANCISCO, CA 94108 (US)**(57) **ABSTRACT**(73) Assignee: **ECN ENERGIEONDERZOEK**  
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The present invention provides a method of manufacturing a crystalline silicon solar cell, comprising: —providing a crystalline silicon substrate having a front side and a back side; —forming a thin silicon oxide film on at least one of the front and the back side by soaking the crystalline silicon substrate in a chemical solution; —forming a dielectric coating film on the thin silicon oxide film on at least one of the front and the back side. The thin silicon oxide film may be formed with a thickness of 0.5-10 nm. By forming an oxide layer using a chemical solution, it is possible to form a thin oxide film for surface passivation wherein the relatively low temperature avoids deterioration of the semiconductor layers.

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